



IPW
PATENT
8007-1116

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takashi SUEYOSHI et al.

Conf. 1846

Application No. 10/594,221

Group 4145

Filed September 25, 2006

Examiner O. Ojurongbe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED
PRODUCT THEREOF

AMENDMENT

Assistant Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 29, 2008

Sir:

In response to the Official Action mailed April 29, 2008, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 6 of this paper.

An **Appendix** is attached which follows the signature page of this paper.